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DNP = DO NOT POPULATE AT ASSEMBLY

C2_P0_1

O2-A1 Sensor will be placed in this location.
Assembly Note

- ZZ1: This Assembly Note is for PCB labels only.
- ZZ2: These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ3: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4: These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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